

	Manufacturing Procedure	Procedure #: MFG038 Rev. B	Date: 2/1/2024
		Page #: Page 1 of 3	
Title: Chip Bonder Storage, Issuance and Usage			

<u>Revision</u>	<u>Description of Change</u>	<u>Date Effective</u>	<u>Author</u>
A	Initial Release	06/04/99	S. Gomez
B	Modified:,7.1,8.1,8.2,8.3 Added: 5.1,5.2, 9.4.3 Removed 9.1.2, 3.2, 9.2 & 9.3 , 6.2	2/1/2024	Mario Baltier

Originator

Name
Title

Name
Title

Title:

Chip Bonder Storage, Issuance and Usage**1.0 Purpose**

- 1.1 This procedure defines the required handling methods essential for chip bonding epoxy adhesive used in the bottom-side attachment of SMT components to PCBs.

2.0 Scope

- 2.1 The content of this procedure covers all areas of responsibility as they apply to the receiving, storage, issuance, and usage of chip bonding epoxy.

3.0 References

- 3.1 SOP 26 Stockroom
- 3.2 Applicable Material Safety Data Sheet (MSDS)

4.0 Definitions

- 4.1 Tube or syringe - The hypodermic-style container that contains the epoxy.
- 4.2 PCB - Printed Circuit Board.
- 4.3 Epoxy - Chip bonding material.

5.0 Responsibilities

- 5.1 Engineering and department supervisors are responsible for logging in all solder wire, wave solder and hand soldering flux, wave solder masking glue, and any other type of chemical used on the floor using form (PMFG249)
- 5.2 Department supervisor and engineers must conduct a monthly walk through of the floor and remove any expired chemical or solder wire from the storage or the floor.

6.0 Equipment

- 6.1 KDS 806 Foot Valve (Kahnetics Dispensing Systems)

7.0 Materials

- 7.1 LOCTITE 368 epoxy or any other LOCTITE epoxy used by SMT for chip bonding purposes.
- 7.2 Disposable wipes or clean rags

8.0 Records

Title:

Chip Bonder Storage, Issuance and Usage

- 8.1 Chemical /solder bar wire log PMFG249
- 8.2 The total retention period for the documents listed by Meritronics, is indicated on the Master Forms Listing (PDO025) under the column heading, Record Retention. When the records are no longer in an active status they will be forwarded to Document Control and filed/maintained in accordance with SOP 29.
- 8.3 The production area will make entries to the Chemicals / Solder Paste Log form recording date and time the epoxy is received in SMT and issued to machine operators. For storing chip bonder/epoxy for long period of time keep it on the solder paste refrigerator.

9.0 Procedure

- 9.1 Receiving
- 9.1.1 Receiving shall forward newly received epoxy to SMT.
- 9.2 Usage
- 9.4.1 Take out tubes from the refrigerator as required and install on the KDS 806 Foot Valve or use it at the printer machine.
- 9.4.2 At the end of the shift, remove the tube from the KDS machine, clean stencil used at the printer machine, and store it into refrigerator.
- 9.4.3 Use the oldest date code tube first
- 9.4 Cleaning and Safety
- 9.5.1 Clean excess epoxy from the KDS needle tip and the printer machine at the end of the shift.
- 9.5.2 Wash hands thoroughly with soap and water before eating, drinking, or smoking.